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## TABLE OF CONTENTS

|   |    |
|---|----|
| Reliable Study for Fine Line RDL Fan Out Multi Chip Module.....   | 34 |
| <i>Jolin Chen, Mike Tsai, Bradley Liu, Hsing-Yu Liu, David Wang, Yu-Po Wang</i>   |    |
| An Effective Uniformity Improvement for Fan-Out Panel Level Packaging Electroplating.....   | 38 |
| <i>Chin-Ting Liao, Boyin Wu, Mingtzung Kuo, Ling-Yuan Chang, Burnet Wang, Jeffrey Yang, Jen-Kuang Fang</i>  |    |
| Chiplet Solution with FO-MCM Package in Edge and Cloud Computing (IMPACT 2023).....   | 42 |
| <i>David Ho, Po Yuan James Su, Jacy Pu, Yu Po Wang</i>  |    |
| Simulation Modeling of 600mm X600mm Fan-Out Panel Level for Warpage Behavior Based on<br>Chip First.....  | 46 |
| <i>Kuo-Ching Cheng, Bo-Heng Chen, Cong-Wei Chen, Ya-Fang Chan, Burnet Wang, Jeffrey Yang, Jen-Kuang Fang</i>  |    |
| A 2 Mm Glass-Embedded Fan Out Antenna in Packaging (FO_AiP) for 60 GHz mmWave<br>Applications.....  | 50 |
| <i>Ying Hsuan Chen, Ben-Je Lwo, Yu-Chen Liu</i>   |    |
| Combining Process Modeling and Machine Learning Technology to Predict the Warpage of the<br>Panel-Level Packaging After Debonding .....                                 | 54 |
| <i>Y. C. Chen, H. L. Chen, K. N. Chiang</i>   |    |
| Thermal Design of Direct Cooling Power Module for EV Applications.....  | 59 |
| <i>Chun-Kai Liu, Yao-Shun Chen, Yuan-Cheng Huang, Tan-Yi Chang, Jia-Shuo Hsing</i>  |    |
| Comprehensive Study on the Reliability of IGBT Module Bonding Process on the Surface<br>Microstructure of Heat Dissipation Substrate.....                               | 63 |
| <i>H. K Hsieh, Y. Y. Lu, M. Y. Hsu, C. W. Huang, M. Y. Pan</i>  |    |
| Reliability Performance Study of Molding Compounds on High Voltage Molded Leaded Package .....  | 67 |
| <i>April Joy Garete, Zhiwen Li, Yee Wai Fung, Wai Man Wong</i>  |    |
| Realization of Sub-4 $\mu\text{m}$ Laser Microvia on ABF.....   | 71 |
| <i>Toshio Otsu, Shuntaro Tani, Tomoharu Nakazato, Hiroharu Tamaru, Kazuyuki Sakaue, George Okada, Naoyuki Nakamura, Junichi Nishimae, Ryo Miyamoto, Yohei Kobayashi</i> |    |
| Polymer Hybrid Bonding Using Copper Paste and Photosensitive Adhesive for Copper-Copper<br>Bonding at 200-250°C.....  | 74 |
| <i>Hirokatsu Sakamoto, Tadashi Teranishi, Rumi Nagai, Takanori Kobatake, Kouichi Takawaki, Motoharu Haga, Akihiko Happoya</i>   |    |
| Alternative 3D Double Side Molded SiP for 5G Communication.....   | 78 |
| <i>Shen-Yu Yang, Yu-Wen Tong, Jing-Jun Lin, Jui-Hao Yang, Chih-Hung Peng, Chao-Chieh Chan</i>   |    |
| Low Temperature Double Pulse Test Platform for Testing Power Modules.....   | 82 |
| <i>Chih-Chiang Wu, Uma Sankar Rout</i>  |    |
| Development of Raman Spectroscopy for Defect Analysis in SiC Devices.....   | 86 |
| <i>A. Myalitsin, T. Yoda, T. Ohba</i>   |    |

|   |     |
|---|-----|
| Reliability Studies of Novel Au-Coated Ag (ACA) Bonding Wires.....  | 88  |
| <i>Randolph E. Flauta, April Joy Garete, Sreetharan Sekaran, Haibin Chen</i>  |     |
| Analysis of Panel Warping for Multilayer RDL Process and Extraction of Dielectric Properties of<br>Photosensitive Polyimide on Fan-Out Panel Level Packaging.....                                     | 92  |
| <i>Ching-Yuan Ho, Po-Yang, Hung</i>   |     |
| Photosensitive Polyimides Compositions with Low Dielectric Property and Good Flexibility<br>Corresponding to Redistribution Layers for Next Generation Heterogeneous Integration<br>Technologies..... | 95  |
| <i>Takashi Tazaki, Takashi Yamaguchi, Taiyou Nakamura, Madoka Yamashita</i>   |     |
| A Study of Adhesion Enhancement for Porous Nickel Plating Treated Surface.....  | 99  |
| <i>Yu-Ning Tsai, Chisa Fukuda, Koya Takahashi, Yoshiko Takahashi, Fumiyoshi Kawashiro,<br/>Takamitsu Noda</i>   |     |
| Interfacial Microstructure Evolution of Low Melting Point Alloy Joints After Thermal Treatments.....  | 102 |
| <i>Cheng-Lun Chen, Liang-Yih Hung, Yueh Yang Lee, Chih-Yuan Shih, Yu-Po Wang</i>  |     |
| Enhancement of Thermal Cycle and Drop Shock Reliability at Board Level with Developed Solder<br>Composition by Optimized Bi, Cu, Ni Contents in Lead Free Solder Composition .....                    | 106 |
| <i>J. Y. Son, S. G. Lee, J. W. Park, Y. W. Lee, S. B. Jung</i>  |     |
| The Effect and Application of Low VOC Automatic Cleaning Process.....   | 111 |
| <i>Ander Hsieh, Mike Huang, Johnny Ch Chen, Michael Yeh, Winter Huang, Justin Sw Yang,<br/>Eric Chou</i>  |     |
| Novel Ultra-Low Dielectric Loss Tangent Resin with High Flame Retardancy for High-Frequency<br>Printed Wiring Boards .....  | 114 |
| <i>Daisuke Ito, Shinsuke Ishikawa, Keizo Inoue, Daiji Ikeda, Teruhiko Miki, Yuichi Fujioka,<br/>Akihiko Happoya</i>   |     |
| Novel Multi-Layered PTFE PCB Fabrication Method for mm-Wave Era .....   | 118 |
| <i>Tatsunari Koyama, Kojiro Iwasa, Yusuke Natsuhara, Takeshi Okunaga, Kaoru Ishida</i>  |     |
| Reducing Carbon Footprint by 75%: Advancing Electronics Manufacturing with Metal Inkjet<br>Printing Technology .....  | 122 |
| <i>Keisuke Ito, Shinya Shimizu</i>  |     |
| A Novel Surface Finish Can Achieve Robustness Against Copper Creep Corrosion for Better<br>Reliability of Printed Circuit Boards (PCBs) .....   | 126 |
| <i>Kunal Shah, Dem Lee, Jeffrey Lee</i>   |     |
| Modeling and Predicting the Beam Properties from Grating Structures Using Deep Neural Network.....  | 133 |
| <i>Yu Dian Lim, Peng Zhao, Luca Guidoni, Jean-Pierre Likforman, Chuan Seng Tan</i>  |     |
| Use Artificial Neural Network to Fit Stress-Strain Curve of Chaboche Model on Lead-free Solder<br>SAC305 .....  | 137 |
| <i>C. E. Lee, Cadmus Yuan, K. N. Chiang</i>   |     |
| Fitting Solder305 Anand Model Parameters with Artificial Neural Networks .....  | 143 |
| <i>Qinghua Su, Cadmus Yuan, K. N. Chiang</i>  |     |
| High-Reliability Solder Pastes for Automotive Applications Reinforcement.....   | 148 |
| <i>Chih-Yang Weng, Kuo-Hua Heish, Chao-Chieh Chan</i>   |     |

|  |     |
|--|-----|
| Precise Warpage Control Technology for 12-Inch Bumpless Via-Last Chip-on-Wafer (COW) by Finite Element Method (FEM) .....  | 152 |
| <i>Wataru Doi, Tatsuya Funaki, Kyosuke Kobinata, Koji Miyamoto, Takayuki Ohba</i>  |     |
| Conversion of Perhydropolysilazane into SiO <sub>2</sub> Using Plasma Treatment for Wafer Bonding.....   | 156 |
| <i>Kai Takeuchi, Daiki Nemoto, Tadatomo Suga, Eiji Higurashi</i>   |     |
| Advanced Optical Metrology for Stability Monitoring of Polyimide Curing Process .....  | 159 |
| <i>Wen-Yi Lin, Kan-Ju Yang, Chia-Peng Sun, An-Dih Yu, Bei-Chun Huang, Kai-Cheng Chen, Yu-Sheng Wang, Cheng-Xuan Wu, Chien-Chen Li, Zhi-Hua Zou, Chien-Li Kuo</i> |     |
| A New X-Ray Source Technology for Demanding SMT and Semiconductor Inspection (IMPACT 23, S20-3) .....  | 163 |
| <i>Keith Bryant</i>  |     |
| Novel Feature Extraction Enhances YOLO on FOCoS RDL Recognition.....   | 168 |
| <i>Jen-Kuang Fang, Wen-Long Lu, Chao-Kai Hung, Peng Yang, Chien-Wei Chang</i>  |     |
| Evaluation of High-Speed Signal Transmission Characteristics of Self-Assembling Anisotropic Conductive Adhesives (SACA) .....                                    | 171 |
| <i>Eakhwan Song, Changhoon Sim, Kyungsub Lee, Tai Woong Ha, Sanguk Lee, Jiseong Kim</i>  |     |
| A Precision Enhancement Deep Learning Framework for Package Substrate Defect Detection .....   | 174 |
| <i>Yi-Chung Hsu, Wong-Shian Huang</i>  |     |
| Machine Learning in Integrated Circuit Substrate Electrical Test (IMPACT 2023).....  | 178 |
| <i>Jung-Pin Lai, Ying-Lei Lin, Yu-Hui Liu, Ho-Chuan Lin, Chih-Yuan Shih, Yu-Po Wang, Ping-Feng Pai</i>   |     |
| Research on Thermal Simulation Analysis of Chip-On-film.....   | 183 |
| <i>Jiun-Ming Chiu, Jen-Chieh Liu</i>   |     |
| Improved Compact Thermal Model for Over-Molded Packages .....  | 187 |
| <i>Lev Tseng, Yu-Hsiang Chang, Bo-Yu Huang, Meng-Hsueh Yang, Ying-Xu Lu, Hung-Hsien Huang, Hui-Chuang Liu</i>  |     |
| Quick Assessment Methodology for Thermal Impedance Prediction Apply to IC Package.....   | 191 |
| <i>Jin Yuan Lai, Shin Yueh Yang, Yeow Chon Ong, Fa Xing Che, Hong Wan Ng</i>   |     |
| AC Noise Enhancement with Fan-Out Embedded Bride Package Solution.....   | 195 |
| <i>Feng Kao, David Wang, Teny Shih, Yu-Po Wang</i>   |     |
| Solution Insight of Platform Printed Circuit Board Fiber-Wave Resonance Beyond 28 GHz High Speed SerDes Application .....  | 199 |
| <i>Hellen Lo, Chuck Lin, Jerry Syue, Cooper Li</i>   |     |
| Chipset Pin Pattern Design Impact on High-Speed Channel Characteristics and Electrical Validation .....  | 203 |
| <i>Jimmy Hsu, Brian Ho, Chiew Yee Ho, Cheng-En Chang, Ryan Chang, Xinjun Zhang, Weizhe Li, Harrison Xue</i>  |     |
| High Q-Factor 3D Tall Copper Pillar Inductor on a Wafer-Level Package for RF System Application .....  | 207 |
| <i>Cheng-Ting Chen, Pao-Nan Lee, Wei-Chu Hsu, Min-Tzu Hsu, Hung-Yi Lin</i>   |     |

|   |     |
|---|-----|
| Difference Frequency of EMI Shielding Solutions for SiP Module .....  | 211 |
| <i>Mike Tsai, Ryan Chiu, James Lin, Ming-Fan Tsai, Eddie Zheng, Dave Chen, Serina Yu, Karina Chang, Erico Yang, Tim Chang, J. Y. Chen</i>   |     |
| Non-PTFE Material for 77GHz Antenna Application .....   | 215 |
| <i>Chieh-Sen Lee, Wallace Chen, John Chiu, Shao-Wei Hsu, Pierce Lin, Roger Chang</i>  |     |
| A 3.5 GHZ Low-Noise Amplifier with TR Switch Package.....   | 218 |
| <i>Tanvir Islam, Wen-Cheng Lai, Ming-Ru Xie, Jin-Wei Hsu, Shang-You Huang</i>   |     |
| OSP and Cleaning Chemistry Interaction - Not All Things Are Created Equal.....  | 222 |
| <i>Frank Xu, John Fudala, Michael Orsini, Robert Farrell, Martin Bunce, Haley Reid</i>  |     |
| Smart Electroless Copper Bath for SAP Applications .....  | 226 |
| <i>Stefanie Manuela Bremmert, Sascha Dieter, Wolfgang Friz, Laurence John Gregoriades, Sandra Röseler, Edith Steinhäuser</i>  |     |
| Electrical Conductivity Control of Stretchable Printed Wires for In-Mold Electronics Applications .....   | 230 |
| <i>Reina Oshima, Takanori Fukushima, Masahiro Inoue</i>   |     |
| Asymmetric Hybrid PCB Design for Cost-Effective and Performance-Driven Solution in Data Center Platforms.....   | 233 |
| <i>Aje Chang, Alan Sun, Kaspar Tsang, Gause Hu, John Lin, Jimmy Hsu, Brian Ho, Ryan Chang, Thonas Su</i>  |     |
| Mitigate Package Level Crosstalk Using Tabbed Design .....  | 237 |
| <i>Cheng-Yu Tsai, Hung-Chun Kuo, Ming-Fong Jhong, Chen-Chao Wang</i>  |     |
| Integration of Failure and Predictive Analytics for Root Cause(s) of Early Lifetime Cracks in Ceramic Based Probe Card.....   | 240 |
| <i>Pradeep Sharma, Peggy Li, Jackal Hsieh, Ck Yang, Steven A Faillaci, Mf Tsai, Doug Garrett, Edmond Cheng, Paul Chang</i>  |     |
| A New Flex Electroless Nickel Chemistry for Flex ENIG and ENEPIG Applications .....   | 243 |
| <i>Frank Xu, Aparna Iyer, Martin Bunce, Michael Orsini, Jesus Barajas</i>   |     |
| Improvement of Adhesion Between High-Frequency-Compatible Substrates with Low Dielectric Constants and Electroless Plated Copper Films Using a Vacuum Ultraviolet Treatment ..... | 247 |
| <i>Taro Arimoto, Masaki Miura, Fumitoshi Takemoto</i>   |     |
| All-Solution-Processed Metallization of High Aspect Ratio Through Glass Vias (HAR-TGVs) with a High Adhesion Promoting Layer (APL).....   | 251 |
| <i>Yiu-Hsiang Chang, Wei-Yen Wang, Pei-Lien Tseng, Mandakini Kanungo, Scott C. Pollard, Prantik Mazumder</i>  |     |
| Printed Circuit Board (PCB) Design Electrical Characterization and Optimization in Immersion Cooling Environment .....  | 255 |
| <i>Mengen Zan, Shaozheng Hou, Yuanming Hu, Yibo Fan, Huafang Ju, Jimmy Hsu, Yinglei Ren, Lili Deng</i>  |     |
| All-GaN HEMTs and Planar Transformer Based 48V Voltage Regulator Common Module (VRCM) Design.....   | 259 |
| <i>Shijuan Qin, Horthense D. Tamdem, Bryant Tsai, Zhiwei Huang, Shuilin Tian, Feng Huang, Ariel Guo, Weijie Yuan, Mark Cao</i>  |     |
| Ideal Flow Design of the Bending of Bi-Material Sheets.....   | 263 |
| <i>Marina Rynkovskaya, Sergei Alexandrov, Artem Moskovskiy, Konstantin Tsybin, Ruslan Buzin</i>   |     |

|  |     |
|--|-----|
| Development of a Semi-Automatic Probe Card Adjustment Equipment.....   | 267 |
| <i>Fu Chen Gao, Kuo-Wei Chiang, Zhe-Luen Tsui, Cadmus Yuan, Chic Chang Wang</i>  |     |
| Kalman Hidden Markov Model Detect User Gesture on Proximity Capacitive Sensor.....   | 271 |
| <i>Chao-Ting Chu, Zhi-Xuan Lin, Chen-Yu Chang</i>  |     |
| Microcontroller Frequency Domain Converter and Fuzzy Speech Recognition Analysis .....   | 275 |
| <i>Chao-Ting Chu, Wei-Chu Chao, Ze-Wei Huang, Zhi-Xuan Lin</i>   |     |
| Rotation Memory Proximity Two-Dimension Inductance Neural Network Identify Gesture<br>Situation .....  | 279 |
| <i>Chao-Ting Chu, Wei-Chu Chao, He-Xian Lin, Zhi-Xuan Lin</i>  |     |
| Deep Learning for Pig Size Detection in Smart Farm Imaging.....  | 283 |
| <i>Chao-Ting Chu, Zhi-Xuan Lin</i>   |     |
| Discrete Power Board Solution on PDS .....   | 287 |
| <i>Gary Tsai, Denis Chen</i>   |     |
| Fan-Out Wafer-level Packaging Process Integration for Artificial Intelligence Real Dies.....   | 290 |
| <i>T. Y. Ouyang, O. Y. Xiovo, R. S. Cheng, Y. S. Chang, T. Y. Hung, C. K. Lee, Y. M. Lin</i>   |     |
| 3D Fan-Out Wafer Level Packaging with Embedded Chip.....   | 294 |
| <i>Chao Kai Hsu, C. C. Hsiao, Ching Feng Yu</i>  |     |
| High-Speed Channel Design and Correlation Between Signal Integrity and Electrical Validation of<br>Datacenter Platforms .....                                  | 298 |
| <i>Brian Ho, Chiew Yee Ho, Jimmy Hsu, Kuan-Ting Wu</i>   |     |
| PCB Solution with Partial Plane-On-Outer-Layer (POOL) Stackup.....   | 302 |
| <i>Yinglei Ren, Jimmy Hsu, Brett Grossman, Gary Brist</i>  |     |
| X-Ray Photoelectron Spectroscopy (XPS) Investigations to Monitor the Cleanliness of Copper<br>Surfaces During Palladium-Free Colloidal Copper Activation ..... | 305 |
| <i>Ibbi Y. Ahmet, André Beyer, Laurence J. Gregoriades, Julia Lehmann, Yvonne Welz</i>   |     |
| In-Line Sputtered Copper/Aluminum-Doped Zinc Oxide Films on Glass Prepared for Energy-<br>Saving and Antibacterial Function .....                              | 309 |
| <i>Huang-Tian Chan, Shang-Chou Chang, Chuan-An Hsiao, Jian-Syun Wu</i>   |     |
| Optimize Stencil Apertures to Eliminate SMT Solder Defects by Shadow Moiré for Warpage<br>Measurement .....  | 312 |
| <i>Ling-Ying Hong, Yun-Tsung Li</i>  |     |
| Noise Analysis and Improvement of Power Supply Network Based on Power Integrity.....   | 317 |
| <i>Bing-Hong Su, Jie-Song Tang, Hsing-Jen Lee, Ching-Biau Tzeng</i>  |     |
| Low Contact Resistance and Low Temperature Hybrid Bonding with Polyimide and Highly <111>-<br>Oriented Nanotwinned Cu.....                                     | 321 |
| <i>Pin-Syuan He, Kai-Cheng Shie, Chih Chen</i>   |     |
| PCI Express Receiver Channel Signal Quality Validation Method.....   | 324 |
| <i>Dian-Ying Wu, Denis Chen</i>  |     |
| Micro-Defect Failure Analysis in Fan-Out Package and Correspond to Finite Element Method<br>(FEM) Simulation Results.....                                      | 327 |
| <i>Yu-Jen Chang, Yu-Hsiang Hsiao, Yi-Sheng Lin, Wei-Jie Yin</i>  |     |

Decision-Based Virtual Metrology Framework to Improve the Efficiency of Solder Resist Opening  
Qualify Control and an Empirical Study in Printed Circuit Board Manufacturing ..... 330  
*Chen-Fu Chien, Yung-Chen Tai, Yun-Siang Lin*

**Author Index**